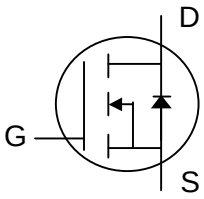
N-CHANNEL ENHANCEMENT-MODE POWER MOSFET

Low gate-charge
Simple drive requirement
Fast switching

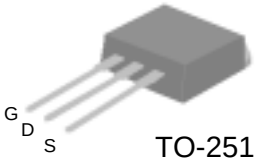


BV_{DSS}	40V
$R_{DS(ON)}$	16mΩ
I_D	42A

Description

The SSM9960H is in a TO-252 package, which is widely used for commercial and industrial surface mount applications, and is well suited for low voltage applications such as DC/DC converters. The through-hole version, the SSM9960J in TO-251, is available for low-footprint vertical

TO-252 (H)



TO-251 (J)

This device is available with Pb-free lead finish (second-level interconnect) as SSM9960GH or SSM9960GJ.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D @ T_A=25°C	Continuous Drain Current, V_{GS} @ 10V	42	A
I_D @ T_A=100°C	Continuous Drain Current, V_{GS} @ 10V	26	A
I_{DM}	Pulsed Drain Current[1]	195	A
P_D @ T_A=25°C	Total Power Dissipation	45	W
	Linear Derating Factor	0.36	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter		Value	Unit
Rthj-c	Thermal Resistance Junction-case	Max.	2.8	°C/W
Rthj-a	Thermal Resistance Junction-ambient	Max.	110	°C/W

Electrical Characteristics @ T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	40	-	-	V
$\Delta BV_{DSS}/\Delta Tj$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I_D=1mA	-	0.032	-	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A	-	-	16	mΩ
		V_{GS}=4.5V, I_D=18A	-	-	25	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	-	3	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=20A	-	30	-	S
I_{DSS}	Drain-Source Leakage Current (T_j=25°C)	V_{DS}=40V, V_{GS}=0V	-	-	1	uA
	Drain-Source Leakage Current (T_j=150°C)	V_{DS}=32V ,V_{GS}=0V	-	-	25	uA
I_{GSS}	Gate-Source Leakage	V_{GS}= ± 20V	-	-	±100	nA
Q_g	Total Gate Charge[2]	I_D=20A	-	18	-	nC
Q_{gs}	Gate-Source Charge	V_{DS}=20V	-	6	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	12	-	nC
$t_{d(on)}$	Turn-on Delay Time[2]	V_{DS}=20V	-	9	-	ns
t_r	Rise Time	I_D=20A	-	110	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω , V_{GS}=10V	-	23	-	ns
t_f	Fall Time	R_D=1Ω	-	10	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	1500	-	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	250	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	180	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=45A, V_{GS}=0V	-	-	1.3	V
t_{rr}	Reverse Recovery Time	I_S=20A, V_{GS}=0V	-	22	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt = 100A/us	-	27.4	-	nC

Notes:

1.Pulse width limited by safe operating area.

2.Pulse width ≤300us , duty cycle ≤2%.

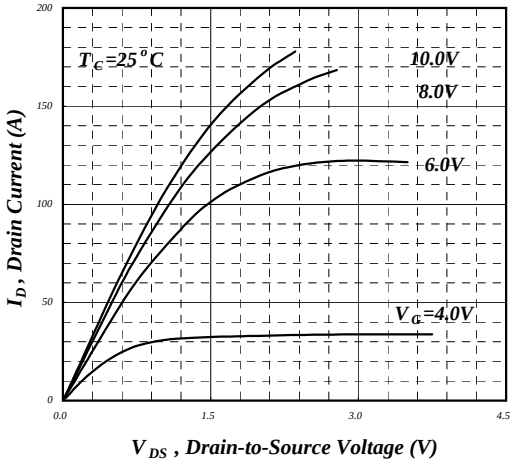


Fig 1. Typical Output Characteristics

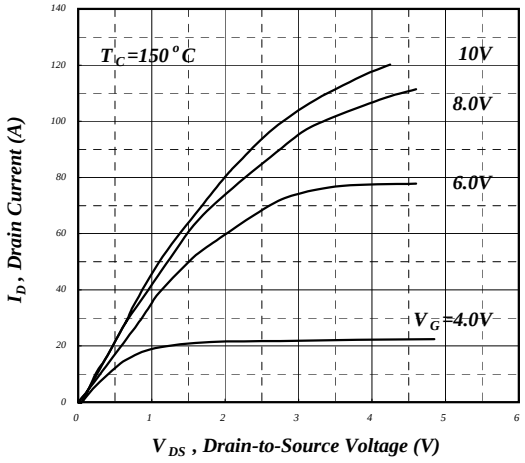


Fig 2. Typical Output Characteristics

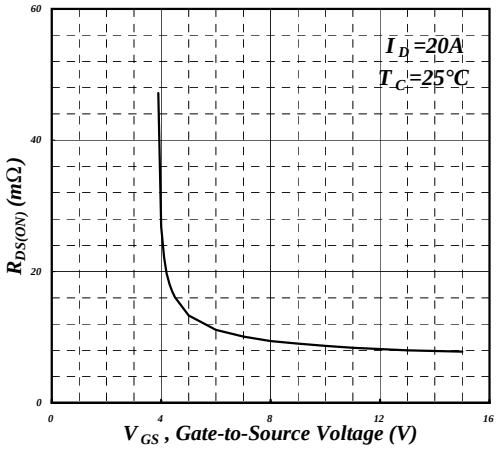


Fig 3. On-Resistance vs. Gate Voltage

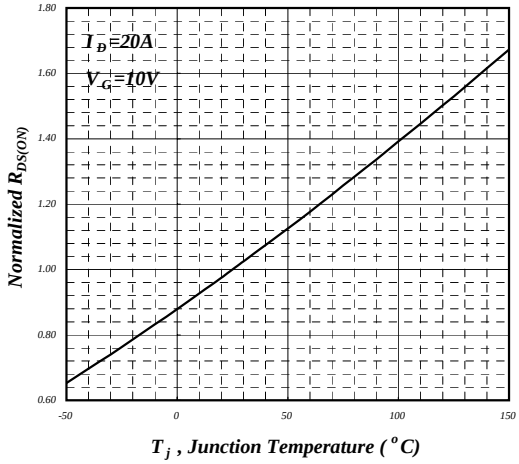


Fig 4. Normalized On-Resistance vs. Junction Temperature

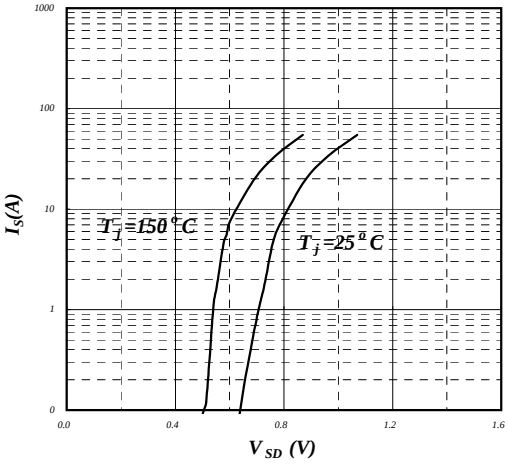


Fig 5. Forward Characteristic of Reverse Diode

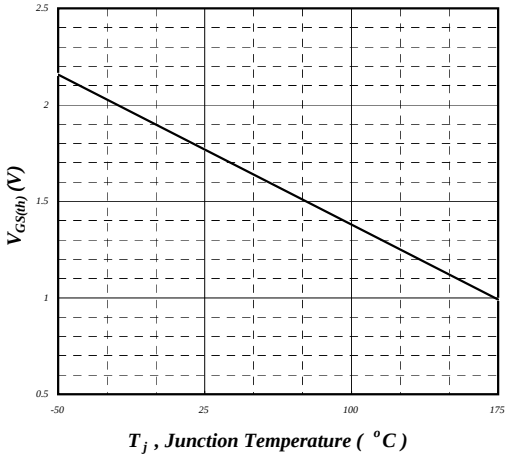


Fig 6. Gate Threshold Voltage vs. Junction Temperature

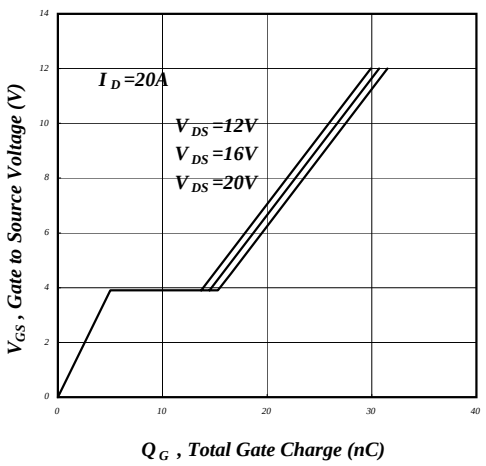


Fig 7. Gate Charge Characteristics

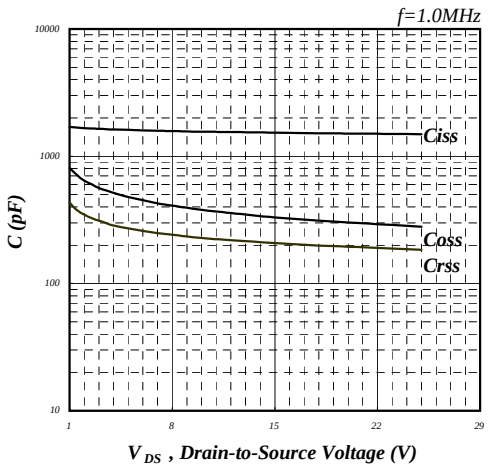


Fig 8. Typical Capacitance Characteristics

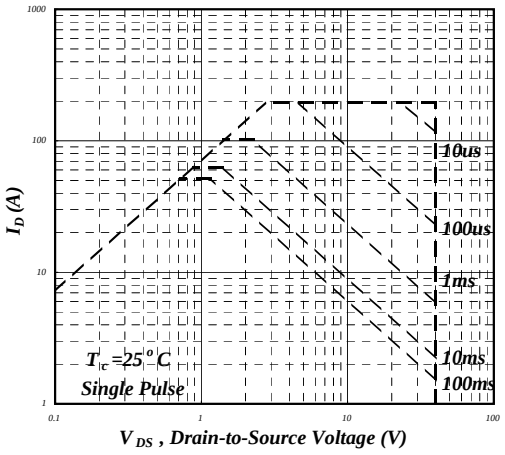


Fig 9. Maximum Safe Operating Area

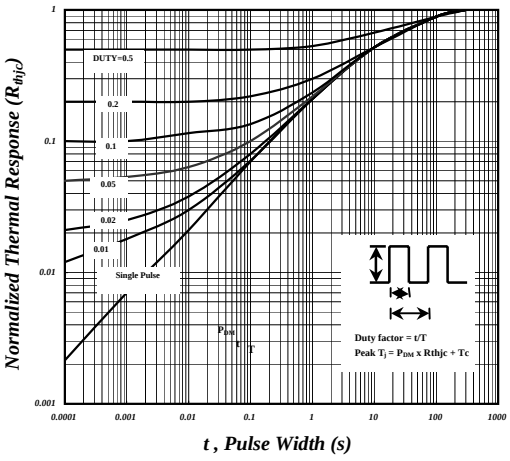


Fig 10. Effective Transient Thermal Impedance

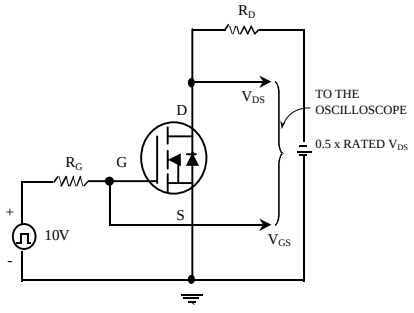


Fig 11. Switching Time Circuit

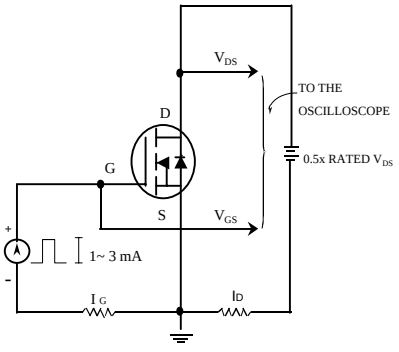


Fig 12. Gate Charge Circuit